

# MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

## DAN202U

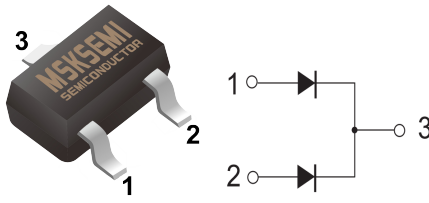

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### Product specification

## FEATURES

- Four types of packaging are available
- High speed
- Suitable for high packing density layout
- High reliability

## Reference News

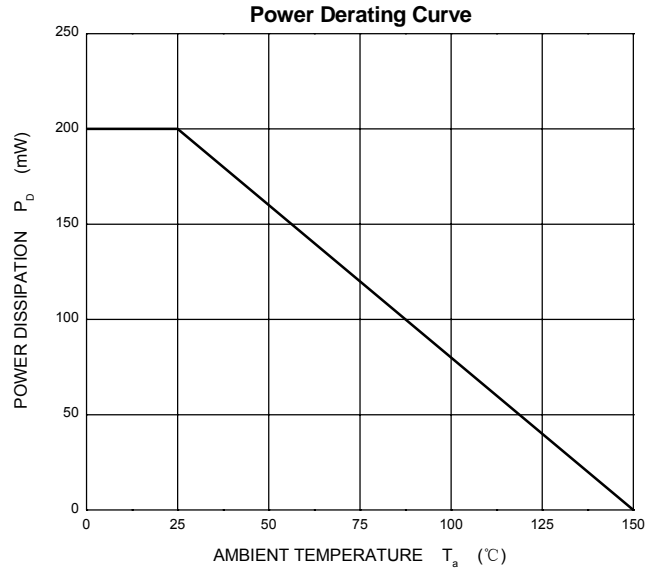
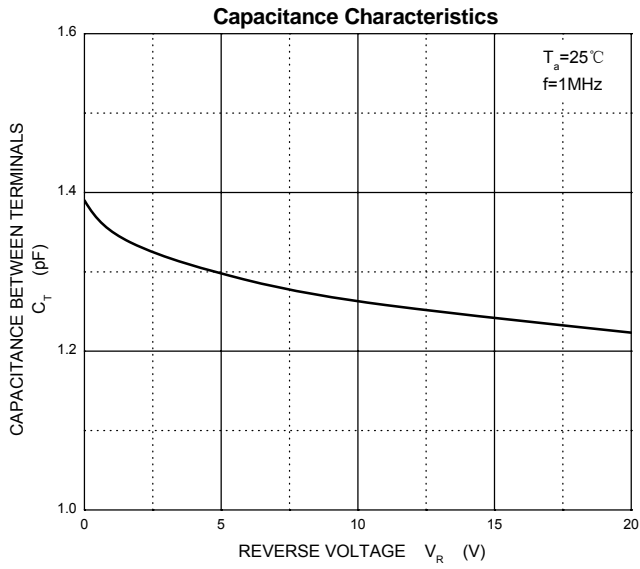
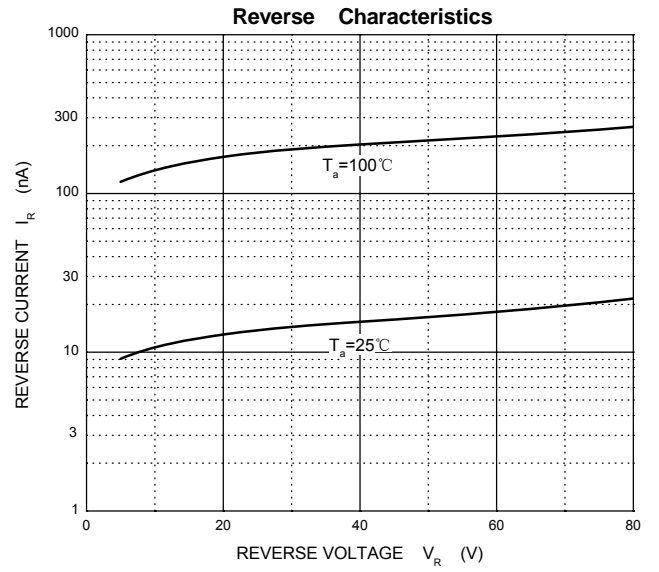
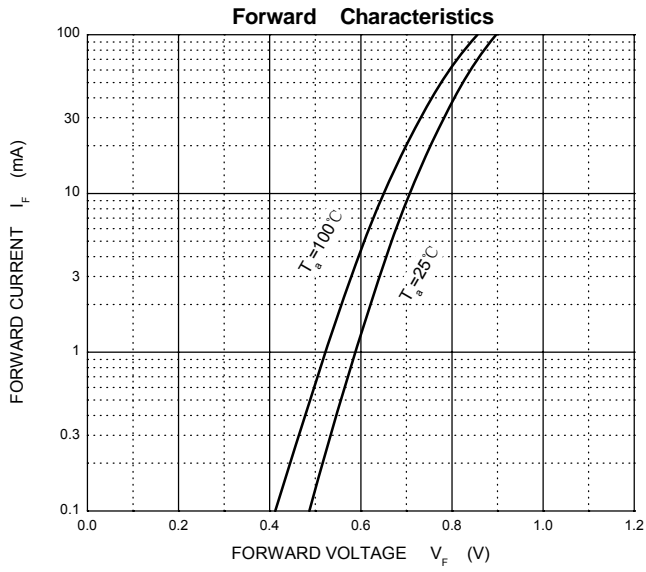
PACKAGE OUTLINE	MARKING
 <p style="text-align: center;">SOT-323</p>	

## Maximum Ratings @Ta=25°C

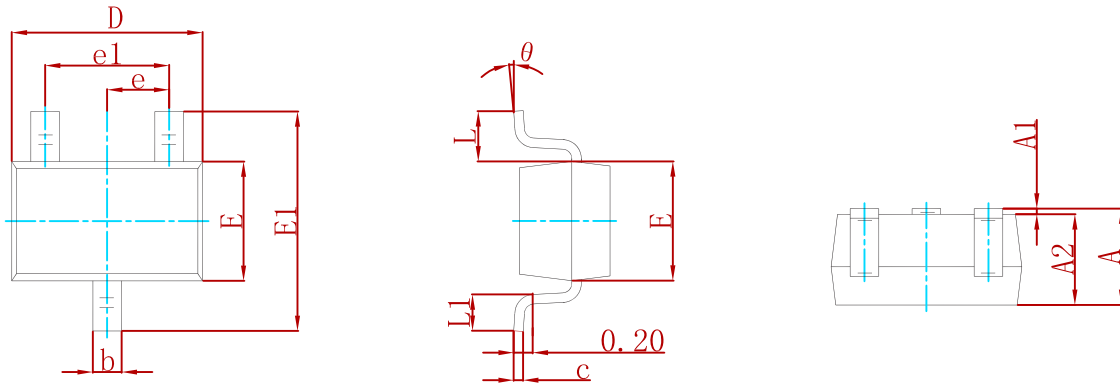
Parameter	Symbol	Limit	Unit
Non-Repetitive Peak Reverse Voltage	$V_{RM}$	80	V
DC Blocking Voltage	$V_R$	80	V
Forward Continuous Current	$I_{FM}$	300	mA
Non-Repetitive Peak Forward Surge Current @t=8.3ms	$I_{FSM}$	2.0	A
Average Rectified Output Current	$I_o$	100	mA
Power Dissipation	$P_D$	200	mW
Thermal resistance From Junction to ambient	$R_{\theta JA}$	625	°C/W
Operation Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~+150	°C

## ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Max	Unit
Reverse breakdown voltage	$V_{(BR)}$	$I_R = 100\mu A$	80		V
Reverse voltage leakage current	$I_R$	$V_R = 70V$		0.1	$\mu A$
Forward voltage	$V_F$	$I_F = 100mA$		1.2	V
Diode capacitance	$C_D$	$V_R = 6V, f = 1MHz$		3.5	pF
Reverse recovery time	$t_{rr}$	$V_R = 6V, I_F = 5mA$		4	ns

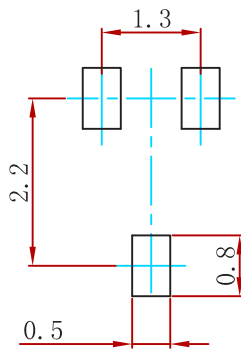


**PACKAGE MECHANICAL DATA**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

**Suggested Pad Layout**



**Note:**

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05\text{mm}$ .
3. The pad layout is for reference purposes only.

**REEL SPECIFICATION**

P/N	PKG	QTY
DAN202U	SOT-323	3000

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